1. Record Nr. UNINA9910300357703321

Titolo	Chemical Skin Injury : Mechanisms, Prevention, Decontamination, Treatment / / edited by Howard I. Maibach, Alan H. Hall
Pubbl/distr/stampa	Berlin, Heidelberg : , : Springer Berlin Heidelberg : , : Imprint : Springer, , 2014
ISBN	3-642-39779-4
Edizione	[1st ed. 2014.]
Descrizione fisica	1 online resource (249 p.)
Disciplina	616.5
Soggetti	Dermatology Emergency medicine Emergency Medicine
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	Skin in the Past and in the Modern Times -- Normal Skin Aspects -- Molecular Dimension of Skin Chemical Aggression -- Damaged Skin -- Practical Aspects of Skin Chemical Exposure and Management.
Sommario/riassunto	This book provides an up-to-date, compact but comprehensive review of chemical skin injuries, differentiating them from thermal skin burns. After an introductory chapter on the history of chemical skin injuries and the scope of the problem, the anatomy, histology, physiology, and immunology of normal skin are described. Mechanisms involved in chemical penetration of normal skin are explained, and the effects of damaged skin on chemical penetration are analyzed. The remainder of the book discusses a variety of clinically relevant aspects, such as the different forms of chemical skin injury, including injuries that arise during skin peeling or due to hair products; preventive measures; emergency treatment; rinsing therapy; medical and surgical treatment; and the importance of providing relevant information to workers. The role of predictive toxicology is also considered. Chemical Skin Injury: Mechanisms, Prevention, Decontamination, Treatment is an ideal resource for readers who want to understand chemical skin injury, to put preventive measures in place, and to respond appropriately should a chemical skin injury occur.